

Wire Bonder

Wire bonding is a technique to make the connection between die or within same die. A soft metal wire is attached to a compatible metallic surface without the use of solder; flux, and in some cases with the use of heat above 150 degrees Celsius. Soft metals include Gold (Au), Copper (Cu), Silver (Ag), Aluminum (Al) and alloys such as Palladium-Silver (Pd-Ag) and others. It performs an ultrasonic bonding. It can operate as a Ball, Wedge, Bump or Peg bonder depending on the bonding tool used.

Process Capabilities:

- Make and Model No: HYBOND Model 626
- WORK STAGE SIZE: 4 inch × 6 inch
- SUBSTRATE TEMPERATURE: Room temperature to 600° C
- Bonding process: Ball, Wedge, Bump or Peg

